

Features

- 1,048,576 word by 16 bit organization
- Single 3.3V \pm 0.3V or 5.0V \pm 0.5V power supply
- Standard Power (SP) and Low Power (LP)
- 1024 Refresh Cycles
 - 16 ms Refresh Rate (SP version)
 - 128 ms Refresh Rate (LP version)
- · High Performance:

		-50	-60	-70
t _{RAC}	RAS Access Time	50ns	60ns	70ns
t _{CAC}	CAS Access Time	13ns	15ns	20ns
t _{AA}	Column Address Access Time	25ns	30ns	35ns
t _{RC}	Cycle Time	95ns	110ns	130ns
t _{PC}	Fast Page Mode Cycle Time	35ns	40ns	45ns

- Low Power Dissipation
 - Active (max) 185 mA / 160 mA / 140 mA
 - Standby: TTL Inputs (max) 2.0 mA
 - Standby: CMOS Inputs (max)
 - 1.0 mA (SP version)
 - 0.2 mA (LP version)
 - Self Refresh (LP version only)
 - 200µA (3.3 Volt)
 - 300μA (5.0 Volt)
- 2 CAS
- · Read-Modify-Write
- RAS Only and CAS before RAS
- · Hidden Refresh
- · Package:
 - TSOP-II 50/44 (400milx825mil)
 - SOJ 42/42 (400mil)

Description

The IBM0118160 is a dynamic RAM organized 1,048,576 words by 16 bits, which has a very low "sleep mode" power consumption option. These devices are fabricated in IBM's advanced $0.5\mu m$ CMOS silicon gate process technology. The circuit and process have been carefully designed to pro-

vide high performance, low power dissipation, and high reliability. The devices operate with a single $3.3V\pm0.3V$ or $5.0V\pm0.5V$ power supply. The 20 addresses required to access any bit of data are multiplexed (10 are strobed with \overline{RAS} , 10 are strobed with \overline{CAS}).

Pin Assignments (Top View)

50/44	TSOP	42/42	2 SOJ
Vcc 1 O I O	50] Vss 49] IO15 48] IO14 47] IO13 46] IO12 45] Vss 44] IO11 43] IO10 42] IO9 41] IO8 40] NC 36] NC 36] NC 35] LCAS 34] UCAS 33] OE 32] A9 31] A8 30] A7 29] A6 28] A5 27] A4 26] Vss	Vcc	42 Vss 41 1015 40 1014 39 1013 38 1012 37 Vss 36 1011 35 1010 34 109 33 108 32 NC 31 LCAS 30 UCAS 29 OE 28 A9 27 A8 26 A7 25 A6 24 A5 23 A4 22 Vss

Pin Description

RAS	Row Address Strobe
LCAS / UCAS	L/U Column Address Strobe
WE	Read/Write Input
A0 - A9	Address Inputs
ŌĒ	Output Enable
I/O0 - I/O15	Data Input/Output
V _{cc}	Power (+3.3V or +5.0V)
V_{SS}	Ground

IBM

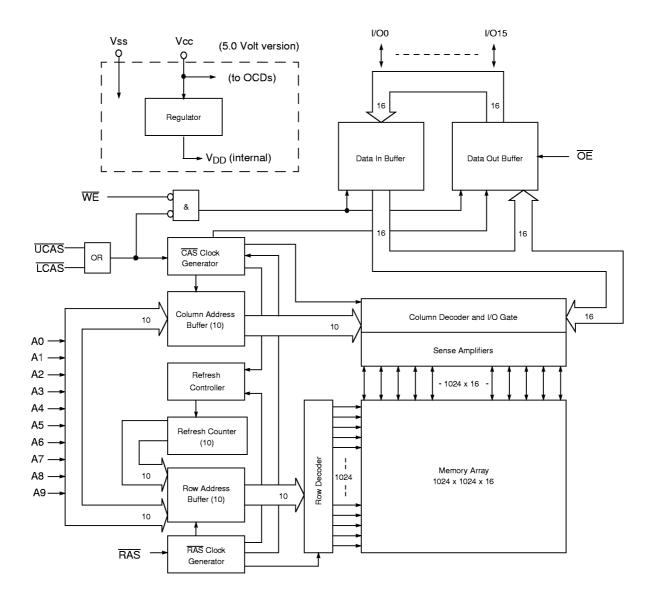
Ordering Information

Part Number	SP / LP	Self Refresh	Power Supply	Speed	Package	Notes
IBM0118160T3 -50	SP	No	5.0V	50ns	400mil TSOP-II 50/44	1
IBM0118160T3 -60	SP	No	5.0V	60ns	400mil TSOP-II 50/44	1
IBM0118160T3 -70	SP	No	5.0V	70ns	400mil TSOP-II 50/44	1
IBM0118160BT3 -50	SP	No	3.3V	50ns	400mil TSOP-II 50/44	1
IBM0118160BT3 -60	SP	No	3.3V	60ns	400mil TSOP-II 50/44	1
IBM0118160BT3 -70	SP	No	3.3V	70ns	400mil TSOP-II 50/44	1
IBM0118160J3 -50	SP	No	5.0V	50ns	400mil SOJ 42/42	1
IBM0118160J3 -60	SP	No	5.0V	60ns	400mil SOJ 42/42	1
IBM0118160J3 -70	SP	No	5.0V	70ns	400mil SOJ 42/42	1
IBM0118160BJ3 -50	SP	No	3.3V	50ns	400mil SOJ 42/42	1
IBM0118160BJ3 -60	SP	No	3.3V	60ns	400mil SOJ 42/42	1
IBM0118160BJ3 -70	SP	No	3.3V	70ns	400mil SOJ 42/42	1
IBM0118160MT3 -50	LP	Yes	5.0V	50ns	400mil TSOP-II 50/44	1
IBM0118160MT3 -60	LP	Yes	5.0V	60ns	400mil TSOP-II 50/44	1
IBM0118160MT3 -70	LP	Yes	5.0V	70ns	400mil TSOP-II 50/44	1
IBM0118160PT3 -50	LP	Yes	3.3V	50ns	400mil TSOP-II 50/44	1
IBM0118160PT3 -60	LP	Yes	3.3V	60ns	400mil TSOP-II 50/44	1
IBM0118160PT3 -70	LP	Yes	3.3V	70ns	400mil TSOP-II 50/44	1
IBM0118160MJ3 -50	LP	Yes	5.0V	50ns	400mil SOJ 42/42	1
IBM0118160MJ3 -60	LP	Yes	5.0V	60ns	400mil SOJ 42/42	1
IBM0118160MJ3 -70	LP	Yes	5.0V	70ns	400mil SOJ 42/42	1
IBM0118160PJ3 -50	LP	Yes	3.3V	50ns	400mil SOJ 42/42	1
IBM0118160PJ3 -60	LP	Yes	3.3V	60ns	400mil SOJ 42/42	1
IBM0118160PJ3 -70	LP	Yes	3.3V	70ns	400mil SOJ 42/42	1

^{1.} SP = Standard Power version (IBM0118160 and IBM0118160B); LP = Low Power version (IBM0118160M and IBM00118160P)



Block Diagram





Truth Table

Function		RAS	LCAS	UCAS	WE	ŌĒ	Row Address	Column Address	I/O0 - I/O15
Standby	***************************************	Н	Н→Х	Н→Х	Χ	Х	Χ	Χ	High Impedance
Read: Word		L	L	L	Н	L	Row	Col	Data Out
Read: Lower Byte		L	L	Н	Н	L	Row	Col	Lower Byte: Data Out Upper Byte: High-Z
Read: Upper Byte		L	Н	L	Н	L	Row	Col	Lower Byte: High-Z Upper Byte: Data Out
Write: Word Early-Write		L	L	L	L	х	Row	Col	Data In
Write: Lower Byte Early-Write		L	L	Н	L	х	Row	Col	Lower Byte: Data In Upper Byte: High-Z
Write: Upper Byte Early-Write		L	Н	L	L	Х	Row	Col	Lower Byte: High-Z Upper Byte: Data In
Read-Modify-Write		L	L	L	H→L	L→H	Row	Col	Data Out, Data In
Fast Page Mode	1st Cycle	L	H→L	H→L	Н	L	Row	Col	Data Out
Fast Page Mode Read	2nd Cycle	L	H→L	H→L	Н	L	N/A	Col	Data Out
Fast Page Mode	1st Cycle	L	H→L	H→L	L	Х	Row	Col	Data In
Write	2nd Cycle	L	H→L	H→L	L	Х	N/A	Col	Data In
Fast Page Mode	1st Cycle	L	H→L	H→L	H→L	L→H	Row	Col	Data Out, Data In
Read-Modify-Write	2nd Cycle	L	H→L	H→L	H→L	L→H	N/A	Col	Data Out, Data In
RAS-Only Refresh		L	Н	Н	Х	Х	Row	N/A	High Impedance
CAS-Before-RAS Refresh		H→L	L	L	Н	Х	Х	N/A	High Impedance
Liiddan Dafaada	Read	L→H→L	L	L	Н	L	Row	Col	Data Out
Hidden Refresh	Write	L→H→L	L	L	Н	Х	Row	Col	Data In
Self Refresh (LP version or	nly)	H→L	L	L	Н	Х	Х	Х	High Impedance



Absolute Maximum Ratings

Comple at	D-v	Ra	ting	Units	Notes
Symbol	Parameter	3.3 Volt Device	5.0 Volt Device	Units	
V _{cc}	Power Supply Voltage	-0.5 to +4.6	-1.0 to +7.0	٧	1
V_{IN}	Input Voltage	-0.5 to min (V _{CC} +0.5, 4.6)	-0.5 to min (V _{CC} +0.5, 7.0)	٧	1
V _{OUT}	Output Voltage	-0.5 to min (V _{CC} +0.5, 4.6)	-0.5 to min (V _{CC} +0.5, 7.0)	٧	1
T _{OPR}	Operating Temperature	0 to +70	0 to +70	°C	1
T _{STG}	Storage Temperature	-55 to +150	-55 to +150	°C	1
P _D	Power Dissipation	1.0	1.0	W	1
I _{OUT}	Short Circuit Output Current	50	50	mA	1

Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a
stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational
sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Recommended DC Operating Conditions (T_A= 0 to 70°C)

	D	3	.3 Volt Devic	:e	5	.0 Volt Devic	е	11-4-	NI-4
Symbol	Parameter	Min.	Тур.	Max.	Min.	Тур.	Max.	Units	Notes
V _{cc}	Supply Voltage	3.0	3.3	3.6	4.5	5.0	5.5	٧	1
V_{IH}	Input High Voltage	2.0	_	V _{CC} + 0.5	2.4	_	V _{CC} + 0.5	٧	1, 2
V_{IL}	Input Low Voltage	-0.5	_	0.8	-0.5	—	0.8	٧	1, 2

^{1.} All voltages referenced to $V_{\rm SS}$.

Capacitance (T_A = 25°C, V_{CC} = 3.3V \pm 0.3V or V_{CC} = 5.0V \pm 0.5V)

Symbol	Parameter	Min.	Max.	Units	Notes
111	nput Capacitance (A0 - A9)		5	pF	1
1	nput Capacitance (RAS, LCAS, UCAS, WE, OE)	_	7	pF	1
c _o c	Output Capacitance (I/O0 - I/O15)	_	7	pF	1

^{1.} Input capacitance measurements made with rise time shift method with $\overline{\text{CAS}} = V_{\text{IH}}$ to disable output.

^{2.} V_{IH} may overshoot to V_{CC} + 1.2V for pulse widths of ≤ 4.0ns with 3.3 Volt, or V_{CC} + 2.0V for pulse widths of ≤ 4.0ns (or V_{CC} + 1.0V for ≤ 8.0ns) with 5.0 Volt. Additionally, V_{IL} may undershoot to -2.0V for pulse widths ≤ 4.0ns with 3.3 Volt, or to -2.0V for pulse widths ≤ 4.0ns (or -1.0V for ≤ 8.0ns) with 5.0 Volt. Pulse widths measured at 50% points with amplitude measured peak to DC reference.



DC Electrical Characteristics $(T_A=0 \text{ to } +70 ^{\circ}\text{C}, V_{CC}=3.3 \text{V} \pm 0.3 \text{V or } V_{CC}=5.0 \text{V} \pm 0.5 \text{V})$

Symbol	Parameter	***************************************	Min.	Max.	Units	Notes
•••••	Operating Current	-50	<u> </u>	185		
I _{CC1}	Operating Current Average Power Supply Operating Current	-60	_	165	mA	1, 2, 3
	(RAS, CAS, Address Cycling: t _{RC} = t _{RC} min.)	-70	_	140		
I _{CC2}	Standby Current (TTL) Power Supply Standby Current (RAS = CAS = V _{IH})		_	1	mA	
	RAS Only Refresh Current	-50	-	185		
I _{CC3}	Average Power Supply Current, RAS Only Mode	-60	_	165	mA	1, 3
	$(\overline{RAS} \text{ Cycling}, \overline{CAS} = V_{IH}: t_{RC} = t_{RC} \text{ min})$	-70	<u> </u>	140		
	Fast Page Mode Current	-50	_	100		
I _{CC4}	Average Power Supply Current	-60	_	90	mA	1, 2, 3
	(RAS = V _{IL} , CAS, Address Cycling: t _{PC} = t _{PC} min)	-70	_	80		
	Standby Current (CMOS)	SP version	_	1	_	
I _{CC5}	Power Supply Standby Current (RAS = CAS = V _{CC} - 0.2V)	LP version	_	0.2	mA	
***************************************	CAS Before RAS Refresh Current Average Power Supply Current, CAS Before RAS Mode	-50	<u> </u>	185		
I _{CC6}		-60	<u> </u>	165	mA	1, 3
	(RAS, CAS, Cycling: t _{RC} = t _{RC} min)	-70	-	140		
	Self Refresh Current, LP version only	3.3V	_	200		
I _{CC7}	Average Power Supply Current during Self Refresh CBR cycle with RAS \geq t _{RASS} (min); CAS held low; WE = V_{CC} - 0.2V; Addresses and $D_{IN} = V_{CC}$ - 0.2V or 0.2V.	5.0V	_	300	μА	
I _{I(L)}	Input Leakage Current Input Leakage Current, any input $(0.0 \le V_{IN} \le (V_{CC} + 0.3V))$, All Other Pins Not Under Test = 0.000	١V	-5	+5	μА	
I _{O(L)}	Output Leakage Current (D_{OUT} is disabled, $0.0 \le V_{OUT} \le V_{CC}$)			+5	μА	
V _{OH}	Output Level (TTL) Output "H" Level Voltage (I _{OUT} = -2.0mA for 3.3V, or I _{OUT} = -5mA for 5.0V)			V _{CC}	٧	
V _{OL}	Output Level (TTL) Output "L" Level Voltage (I _{OUT} = +2.0mA for 3.3V, or I _{OUT} = +4.2mA for 5.0V)		0.0	0.4	٧	

^{1.} $I_{CC1},\,I_{CC3},\,I_{CC4}$ and I_{CC6} depend on cycle rate.

^{2.} I_{CC1} and I_{CC4} depend on output loading. Specified values are obtained with the output open.

^{3.} Address can be changed once or less while $\overline{RAS} = V_{IL}$. In the case of I_{CC4} , it can be changed once or less when $\overline{CAS} = V_{IH}$.



AC Characteristics (T_A = 0 to +70°C, V_{CC} = 3.3V \pm 0.3V or V_{CC} = 5.0V \pm 0.5V)

- 1. An initial pause of 200µs is required after power-up followed by 8 RAS only refresh cycles before proper device operation is achieved. In case of using the internal refresh counter, a minimum of 8 CAS before RAS refresh cycles instead of 8 RAS only refresh cycles is required.
- 2. AC measurements assume t_T=5ns.
- 3. $V_{IH}(min.)$ and $V_{IL}(max.)$ are reference levels for measuring timing of input signals. Also, transition times are measured between V_{IH} and V_{II} .
- 4. When both LCAS and UCAS go low at the same time, all 16 bits of data are read/written into the device. LCAS and UCAS cannot be staggered within the same read/write cycle.

Read, Write, Read-Modify-Write and Refresh Cycles (Common Parameters)

Symbol	Parameter	-	·50	-	-60	-	70	Units	Notes
Бу Шроі	Рагатетег	Min.	Мах.	Min.	Max.	Min.	Мах.	Units	Notes
t _{RC}	Random Read or Write Cycle Time	95		110		130		ns	****************
t _{RP}	RAS Precharge Time	30	_	40	_	50	_	ns	
t _{CP}	CAS Precharge Time	10	_	10	_	10	_	ns	
t _{RAS}	RAS Pulse Width	50	10K	60	10K	70	10K	ns	***************************************
t _{CAS}	CAS Pulse Width	13	10K	15	10K	20	10K	ns	
t _{ASR}	Row Address Setup Time	0	_	0		0	_	ns	•••••
t _{RAH}	Row Address Hold Time	10	_	10	_	10	_	ns	
t _{ASC}	Column Address Setup Time	0	_	0		0	_	ns	
t _{CAH}	Column Address Hold Time	10	_	10	_	10	_	ns	
t _{RCD}	RAS to CAS Delay Time	20	37	20	45	20	50	ns	1
t _{RAD}	RAS to Column Address Delay Time	15	25	15	30	15	35	ns	2
t _{RSH}	RAS Hold Time	13	_	15	_	20	_	ns	
t _{CSH}	CAS Hold Time	50	_	60	_	70	_	ns	
t _{CRP}	CAS to RAS Precharge Time	5	_	5		5	_	ns	
t _{OED}	OE to D _{IN} Delay Time	13		15		15		ns	3
t _{DZO}	OE Delay Time from D _{IN}	0		0		0		ns	4
t _{DZC}	CAS Delay Time from D _{IN}	0		0		0		ns	4
t _T	Transition Time (Rise and Fall)	3	50	3	50	3	50	ns	5

- Operation within the t_{RCD}(max.) limit ensures that t_{RAC}(max.) can be met. t_{RCD}(max.) is specified as a reference point only. If t_{RCD} is greater than the specified t_{RCD}(max.) limit, then access time is controlled by t_{CAC}.
- 2. Operation within the t_{RAD}(max.) limit ensures that t_{RAC}(max.) can be met. t_{RAD}(max.) is specified as a reference point only. If t_{RAD} is greater than the specified t_{RAD}(max.) limit, then access time is controlled by t_{AA}.
- 3. Either t_{CDD} or t_{OED} must be satisfied.
- 4. Either t_{DZC} or t_{DZO} must be satisfied
- 5. AC measurements assume t_T=5ns.



Write Cycle

	Parameter		-50	-60		-70			Notes
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Units	INOTES
t _{wcs}	Write Command Set Up Time	0	_	0	_	0	_	ns	1
t _{WCH}	Write Command Hold Time	10	_	15	_	15	_	ns	
t _{WP}	Write Command Pulse Width	10	_	15	_	15		ns	
t _{RWL}	Write Command to RAS Lead Time	13	_	15	_	20	_	ns	
t _{CWL}	Write Command to CAS Lead Time	13	_	15	_	20	_	ns	
t _{DS}	D _{IN} Setup Time	0	_	0	_	0		ns	2
t _{DH}	D _{IN} Hold Time	10	_	12	_	15	_	ns	2

^{1.} t_{WCS}, t_{RWD}, t_{CWD}, t_{AWD} and t_{CPW} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only. If t_{WCS} ≥ t_{WCS} (min), the cycle is an early write cycle and the data pin will remain open circuit (high impedance) through the entire cycle. If t_{RWD} ≥ t_{RWD} (min), t_{CWD} ≥ t_{CWD} (min), t_{AWD} ≥ t_{AWD} (min), and t_{CPW} ≥ t_{CPW} (min)(Fast Page Mode), the cycle is a Read-Modify-Write cycle and the data out will contain data read from the selected cell. If neither of the above sets of conditions are satisfied, the condition of the data out (at access time) is indeterminate.

^{2.} These parameters are referenced to TCAS or UCAS leading edge in early write cycles and to WE leading edge in Read-Modify-Write cycles.



Read Cycle

O h l	D		-50		-60	-70		11:4-	Notes
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Units	Notes
t _{RAC}	Access Time from RAS	<u> </u>	50	_	60	<u> </u>	70	ns	1, 2, 3
t _{CAC}	Access Time from CAS	_	13	_	15	_	20	ns	1, 3
t _{AA}	Access Time from Address	_	25	_	30	<u> </u>	35	ns	2, 3
t _{OEA}	Access Time from OE	-	13	-	15	_	20	ns	3
t _{RCS}	Read Command Setup Time	0		0		0	_	ns	
t _{RCH}	Read Command Hold Time to CAS	0		0		0	_	ns	4
t _{RRH}	Read Command Hold Time to RAS	0	_	0	_	0	_	ns	4
t _{RAL}	Column Address to RAS Lead Time	25		30		35	_	ns	
t _{CAL}	Column Address to CAS Lead Time	25		30		35	_	ns	
t _{CLZ}	CAS to Output in Low-Z	0		0		0	_	ns	3
t _{OH}	Output Data Hold Time	3		3		3	_	ns	
t _{OHO}	Output Data Hold from OE	3		3		3	_	ns	
t _{OFF}	Output Buffer Turn-Off Delay	_	13	_	15	_	15	ns	5
t _{OEZ}	Output Buffer Turn-Off Delay from OE	_	13	_	15	_	15	ns	5
t _{CDD}	CAS to D _{IN} Delay Time	13	_	15	_	15	_	ns	6

- Operation within the t_{RCD}(max.) limit ensures that t_{RAC}(max.) can be met. t_{RCD}(max.) is specified as a reference point only. If t_{RCD} is greater than the specified t_{RCD}(max.) limit, then access time is controlled by t_{CAC}.
- Operation within the t_{RAD}(max.) limit ensures that t_{RAC}(max.) can be met. t_{RAD}(max.) is specified as a reference point only. If t_{RAD} is greater than the specified t_{RAD}(max.) limit, then access time is controlled by t_{AA}.
- 3. Measured with the specified current load and 100pF.
- 4. Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.
- 5. t_{OFF} (max) and t_{OEZ} (max) define the time at which the output achieves the open circuit condition and are not referenced to output voltage levels.
- 6. Either t_{CDD} or t_{OED} must be satisfied.



Read-Modify-Write Cycle

Symbol	Parameter	-50		-60		-70		Units	NI-t
Symbol		Min.	Max.	Min.	Max.	Min.	Max.	Units	Notes
t _{RWC}	Read-Modify-Write Cycle Time	128	_	150	_	180	_	ns	
t _{RWD}	RAS to WE Delay Time	68	_	80	_	95	_	ns	1
t _{CWD}	CAS to WE Delay Time	31	_	35	_	45		ns	1
t _{AWD}	Column Address to WE Delay Time	43	_	50	_	60	_	ns	1
t _{OEH}	OE Command Hold Time	13	_	15	_	15	_	ns	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,

^{1.} t_{WCS}, t_{RWD}, t_{CWD}, t_{AWD} and t_{CPW} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only. If t_{WCS} ≥ t_{WCS} (min), the cycle is an early write cycle and the data pin will remain open circuit (high impedance) through the entire cycle. If t_{RWD} ≥ t_{RWD} (min), t_{CWD} ≥ t_{CWD} (min), t_{AWD} ≥ t_{AWD} (min), and t_{CPW} ≥ t_{CPW} (min)(Fast Page Mode), the cycle is a Read-Modify-Write cycle and the data out will contain data read from the selected cell. If neither of the above sets of conditions are satisfied, the condition of the data out (at access time) is indeterminate.

Fast Page Mode Cycle

Symbol	Parameter	-50		-60		-70		11-11-	NI-4
Symbol		Min.	Max.	Min.	Max.	Min.	Мах.	Units	Notes
t _{PC}	Fast Page Mode Cycle Time	35	_	40	_	45		ns	***************************************
t _{RASP}	Fast Page Mode RAS Pulse Width	50	200K	60	200K	70	200K	ns	
t _{CPA}	Access Time from CAS Precharge	_	28	_	35	_	40	ns	1
t _{CPRH}	RAS Hold Time from CAS Precharge	30		35		40	<u> </u>	ns	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,

^{1.} Measured with the specified current load and 100pF.

Fast Page Mode Read-Modify-Write Cycle

C	D		-50 -60	-50 -60 -70			Units	NI-4	
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.		Notes
t _{PRWC}	Fast Page Mode Read-Modify-Write Cycle Time	71	_	80	_	95	_	ns	
t _{CPW}	WE Delay Time from CAS Precharge	48	_	55	_	65	_	ns	1

^{1.} t_{WCS}, t_{RWD}, t_{CWD}, t_{AWD} and t_{CPW} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only. If t_{WCS} ≥ t_{WCS} (min), the cycle is an early write cycle and the data pin will remain open circuit (high impedance) through the entire cycle. If t_{RWD} ≥ t_{RWD} (min), t_{CWD} ≥ t_{CWD} (min), t_{AWD} ≥ t_{AWD} (min), and t_{CPW} ≥ t_{CPW} (min)(Fast Page Mode), the cycle is a Read-Modify-Write cycle and the data out will contain data read from the selected cell. If neither of the above sets of conditions are satisfied, the condition of the data out (at access time) is indeterminate.



Refresh Cycle

Symbol	Parameter	-50		-60		-70		Units	Notes
Symbol		Min.	Max.	Min.	Max.	Min.	Max.	UIIIIS	Notes
t _{CSR}	CAS Setup Time (CAS before RAS Refresh Cycle)	5	_	5	_	5	_	ns	
t _{CHR}	CAS Hold Time (CAS before RAS Refresh Cycle)	10	_	10	_	10	_	ns	
t _{WRP}	WE Setup Time (CAS before RAS Refresh Cycle)	10	_	10	_	10	_	ns	
t _{wr} H	WE Hold Time (CAS before RAS Cycle)	10	_	10	_	10	_	ns	
t _{RPC}	RAS Precharge to CAS Hold Time	5	_	5	_	5	_	ns	

Self Refresh Cycle - Low Power version only

S b l	Dava-mastar	-50		-60		-70			N1_1
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Мах.	Units	Notes
t _{RASS}	RAS Pulse Width During Self Refresh Cycle	100	_	100	_	100	_	μs	1
t _{RPS}	RAS Precharge Time During Self Refresh Cycle	89	_	104	_	124	_	ns	1
t _{CHS}	CAS Hold Time From RAS Rising During Self Refresh Cycle	-50	_	-50	_	-50	_	ns	1, 2
t _{CHD}	CAS Hold Time From RAS Falling During Self Refresh Cycle	350	_	350	_	350	_	μs	1, 2

^{1.} When using Self Refresh mode, the following refresh operations must be performed to ensure proper DRAM operation:
If row addresses are being refreshed in an EVENLY DISTRIBUTED manner over the refresh interval using CBR refresh cycles, then only one CBR cycle must be performed immediately after exit from Self Refresh.

Refresh

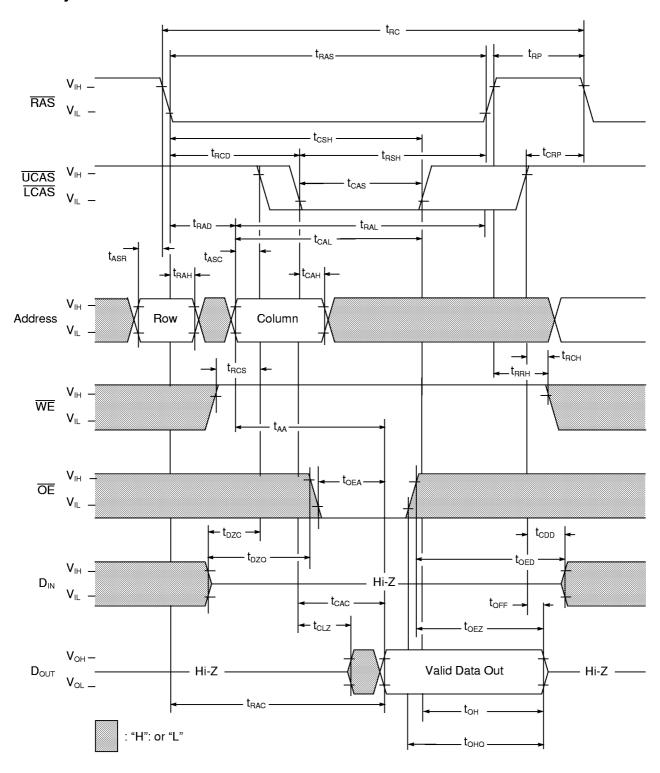
SYMPOL D			-50		-60		-70			
SYMBOL	Parameter		Min.	Max.	Min.	Max.	Min.	Max.	Units	Notes
		SP version	-	16	<u> </u>	16	_	16	ms	1
\REF	Refresh Period	LP version	_	128	_	128	_	128		
1. 1024 cycle	9S.									

If row addresses are being refreshed in any other manner (ROR- Distributed/Burst; or CBR-Burst) over the refresh interval, then a full set of row refreshes must be performed immediately before entry to and immediately after exit from Self Refresh.

^{2.} If $t_{RASS} > t_{CHD}$ (min) then t_{CHD} applies. If $t_{RASS} \le t_{CHD}$ (min) then t_{CHS} applies.

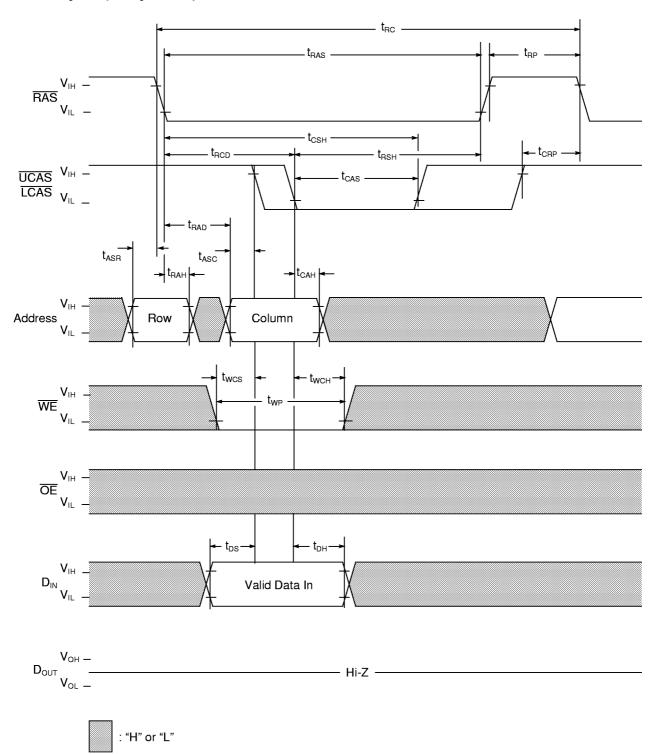


Read Cycle



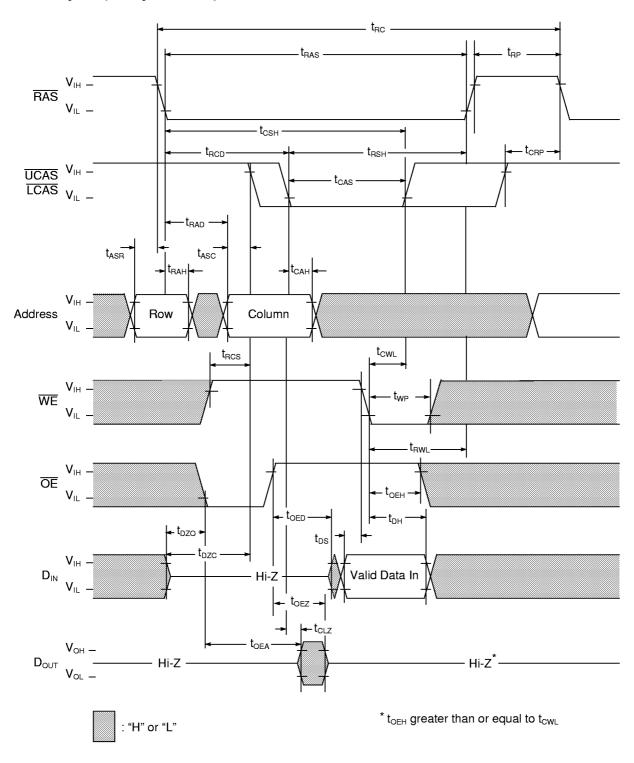


Write Cycle (Early Write)



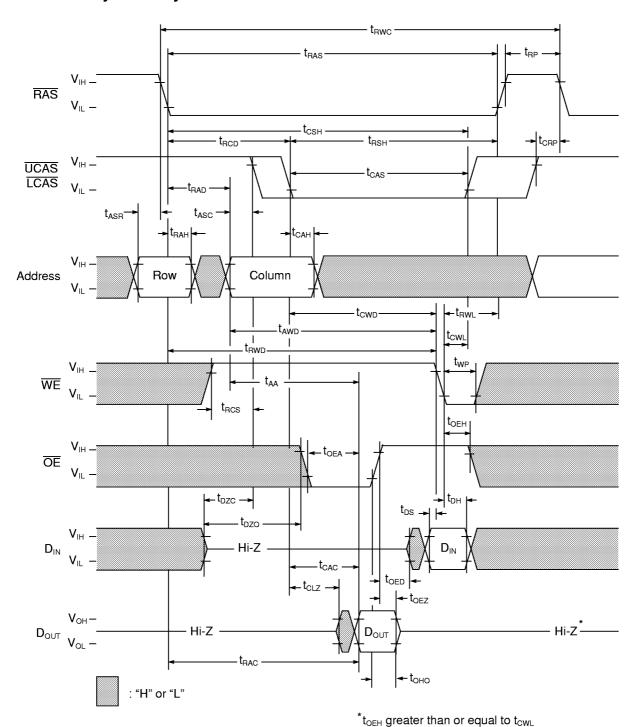


Write Cycle (Delayed Write)



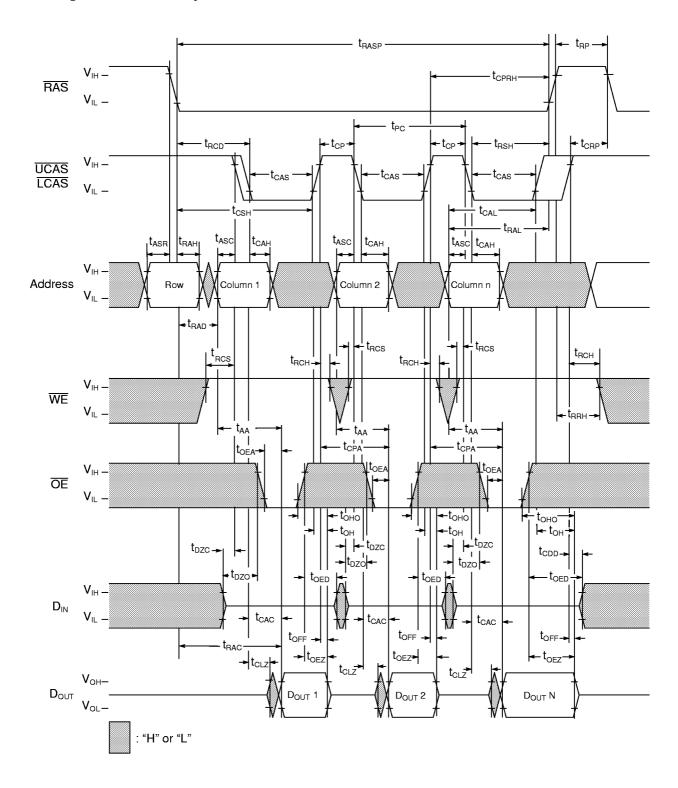


Read-Modify-Write Cycle



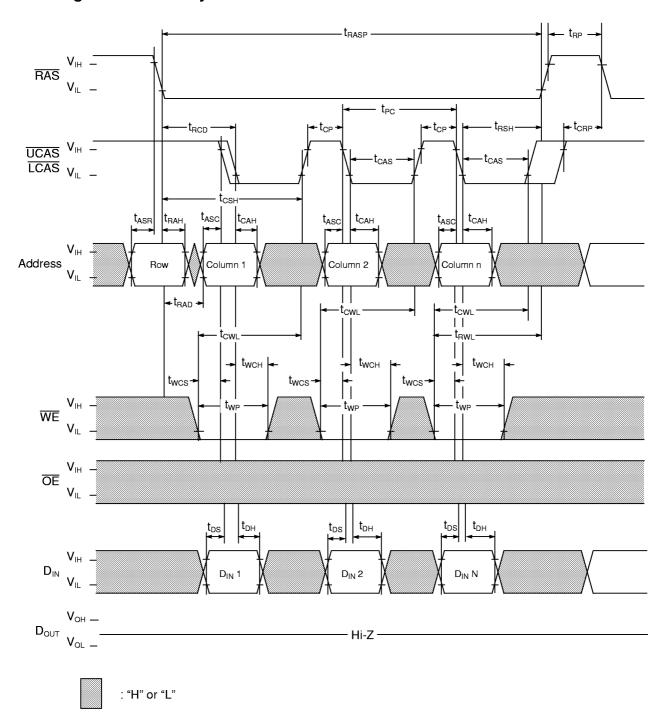


Fast Page Mode Read Cycle



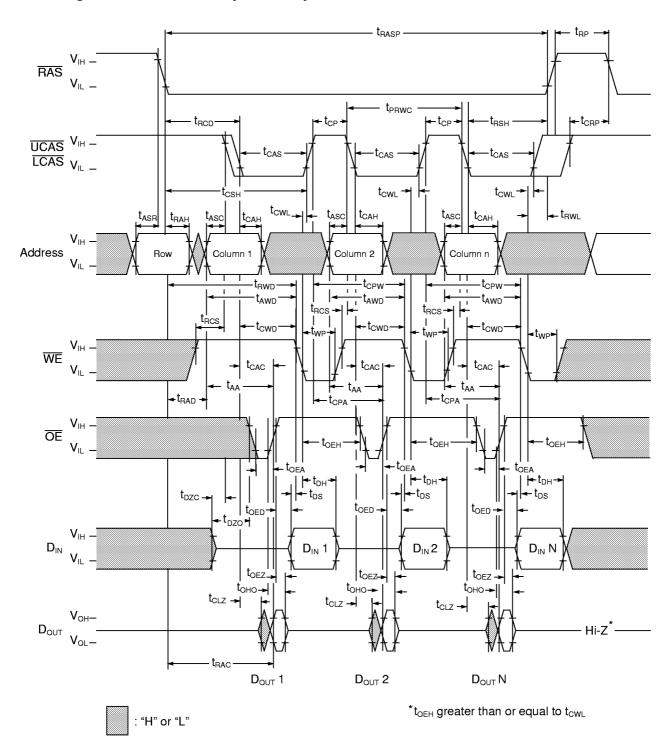


Fast Page Mode Write Cycle



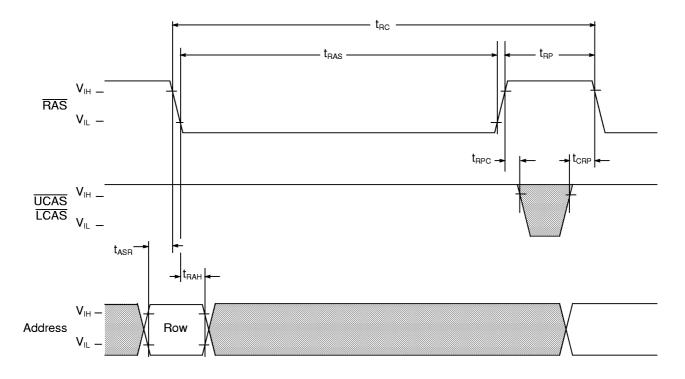


Fast Page Mode Read-Modify-Write Cycle

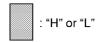




RAS Only Refresh Cycle



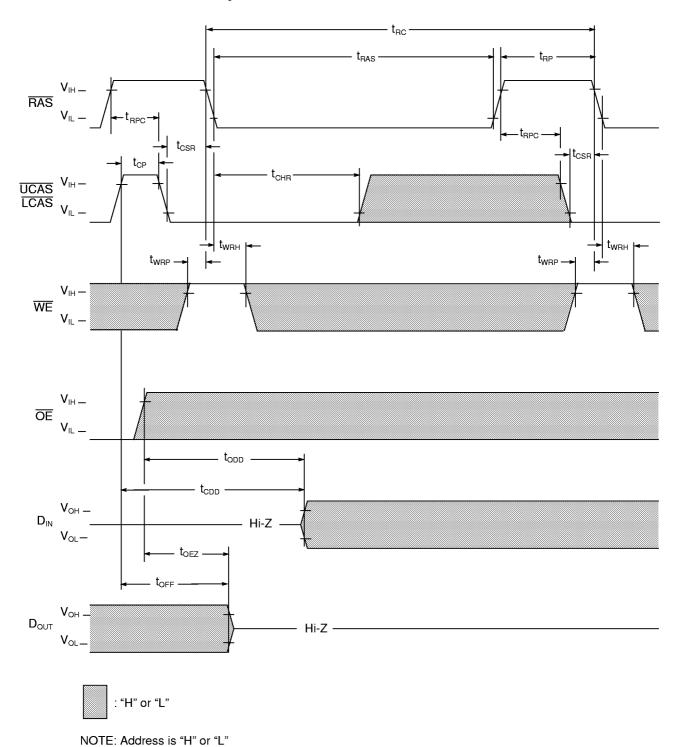
$$\begin{array}{c} V_{\text{OH}-} \\ \\ V_{\text{OL}-} \end{array} \\ \begin{array}{c} \text{Hi-Z} \\ \\ \end{array}$$



NOTE: $\overline{\text{WE}}$, $\overline{\text{OE}}$ and D_{IN} are "H" or "L"

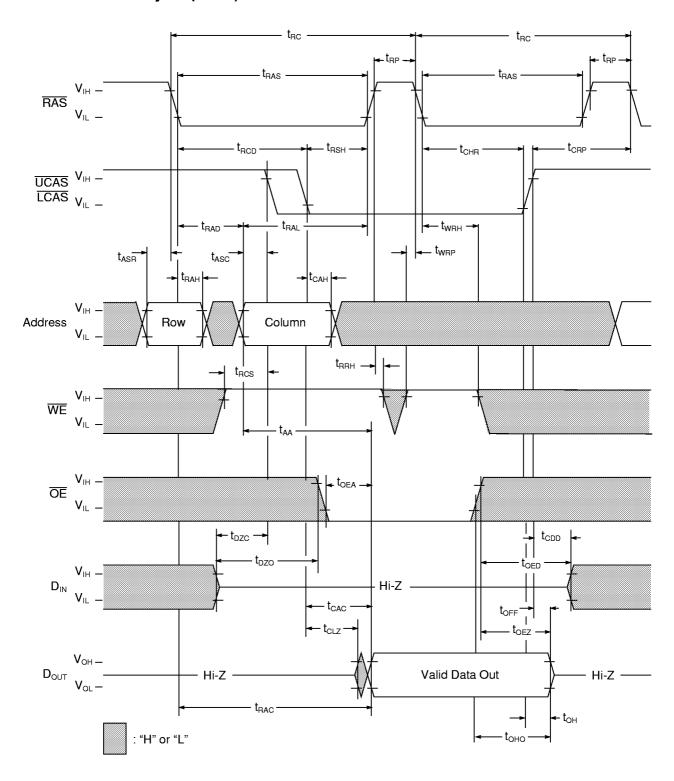


$\overline{\text{CAS}}$ Before $\overline{\text{RAS}}$ Refresh Cycle



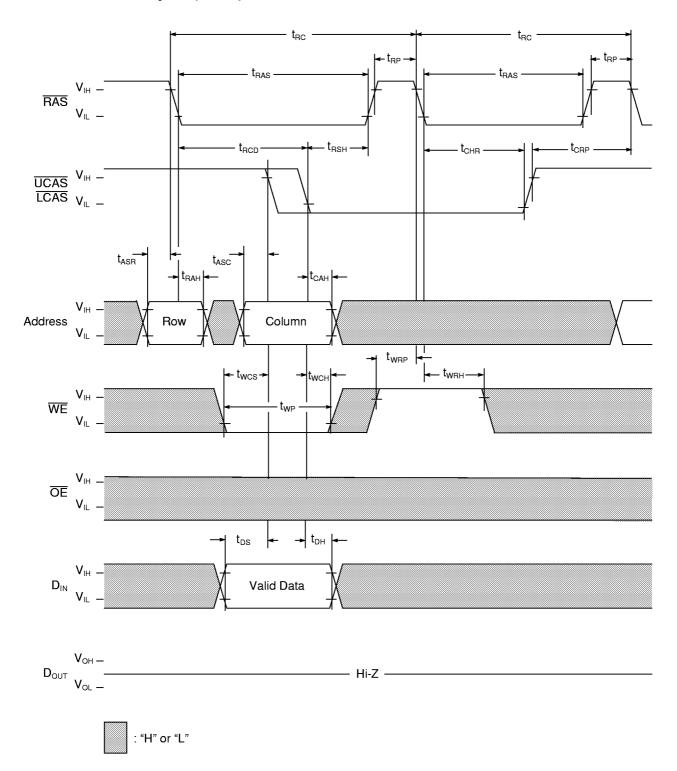


Hidden Refresh Cycle (Read)



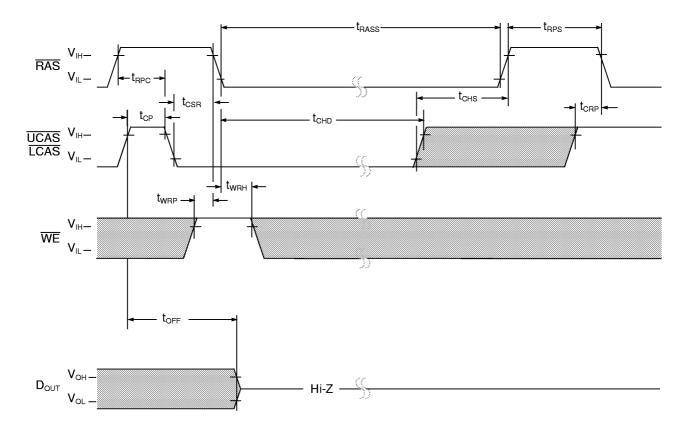


Hidden Refresh Cycle (Write)





Self Refresh Cycle (Sleep Mode) - Low Power version only



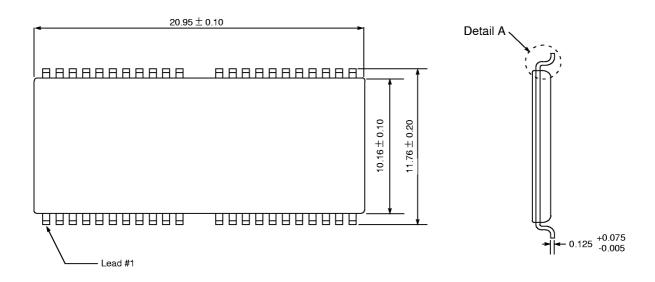


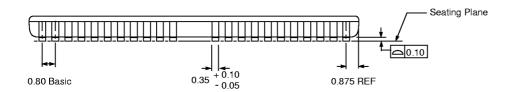
NOTES:

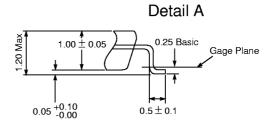
- 1. Address and \overline{OE} are "H" or "L"
- 2. Once \overline{RAS} (min) is provided and \overline{RAS} remains low, the DRAM will be in Self Refresh, commonly known as "Sleep Mode."
- 3. If $t_{\text{RASS}} > t_{\text{CHD}}$ (min) then t_{CHD} applies. If $t_{\text{RASS}} \le t_{\text{CHD}}$ (min) then t_{CHS} applies.



PACKAGE DIMENSIONS (400mil; 50/44 lead; Thin Small Outline Package)



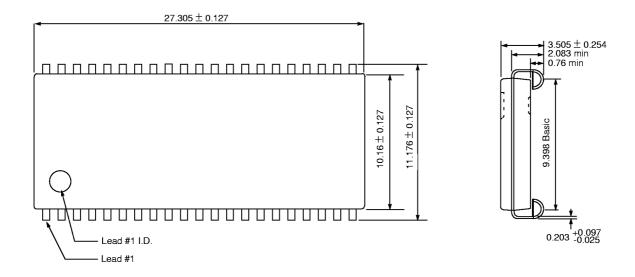


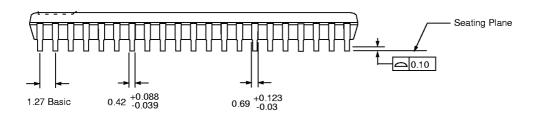


NOTE: All dimensions are in millimeters; Package diagrams are not drawn to scale.



PACKAGE DIMENSIONS (400mil; 42/42 lead; Small Outline J-Lead)





NOTE: All dimensions are in millimeters; Package diagrams are not drawn to scale.



Revision Log

Revision	Contents Of Modification
01/94	Initial Release
06/17/94	Change Fast Page Mode Currents (I _{CC4}) from 85, 75, 65, 55mA to 100, 90, 80, 70mA
09/06/94	Combine the 3.3 Volt and the 5.0 Volt specifications Change the Refresh Period from 256ms to 128ms Change I _{CC1} , I _{CC3} , I _{CC6} from 215, 195, 170, 150mA to 225, 205, 180, 160mA
11/15/95	 lout changed to +2.0 mA and -2.0 mA in DC Electrical Characteristics table. Packaging diagrams modified to clarify lead thickness and standoff height. t_{RPC} min changed from 0 to 5ns. t_{CHR} min changed from 20 to 10ns. Currents in DC Electrical Characteristics table revised. Test Modes and Test Circuit Diagram removed. Rename t_{ODD} to t_{OED}. t_{OED}, t_{CDD}, t_{OEZ}, and t_{OFF} min changed from 20 to 15ns, for the 70ns part. t_{OEH} min changed from 5 to 0ns for all speed sorts. t_{OEH} min changed from 20 to 15ns for the 70ns part. t_{CSR} min changed from 5 to 10ns for all speed sorts. tCAH min changed from 15 to 10ns on 60 and 70ns parts. t_{OFF} max changed from 20 to 15ns for 70ns parts.
12/10/95	 The Low Power and Standard Power Specifications were combined. ES# 43G9387 and ES# 43G9388 were combined into ES# 43G9388. Added Die Rev E part numbers. t_{DH} was reduced from 15ns to 12ns for the -60 speed sort. t_{CHD} was added to the Self Refresh Cycle with a value of 350μs for all speed sorts. The Self Refresh timing diagram was changed to allow CAS to go high t_{CHD} (350μs) after RAS falls entering a Self Refresh. The CBR timing diagram was changed to allow CAS to remain low for back-to-back CBR cycles. WE for the Hidden Refresh Write cycle in the Truth Table was changed from "L" to " H".
09/01/96	 I_{CC2} was changed from 2mA to 1mA. I_{I(L)} and I_{O(L)} were altered from +/- 10uA to +/- 5uA. t_T was initially at a max of 30ns. It has been modified to 50ns for all speed sorts. t_{CPA} was decreased from 30ns to 28ns for the -50 speed sort. t_{RASP} max of 125K was raised to 200K for all speed sorts. t_{RP} was changed from 35ns to 30ns for the -50 speed sort.